

Tech-X Corporation invites you to visit us at Booth #8 at the [IEEE International Power Modulator and High Voltage Conference](#), May 23 - 27 in Atlanta, GA.

We are proud to present our electromagnetic plasma simulation software, VORPAL (<http://vorpalltxcorp.com>). VORPAL 4.0 provides for the first time parallel and multi-core capability to the Windows platform (as with previous versions, VORPAL 4.0 also runs in parallel on the Linux and Macintosh platforms). Let VORPAL 4.0 help you take full advantage of your multi-core desktop computer. Other new capabilities include:

- cylindrical coordinates for electromagnetic simulation
- automated eigenfrequency and eigenmode extraction from time-domain simulation
- new secondary electron models that allow simulations of complex metallic and dielectric boundaries of arbitrary shape without stairsteps
- improved post-processing, including automated import into the VisIt software for advanced visualization

Stop by our table to see a demonstration of any of these new features of VORPAL 4.0. Our technical staff will be available at the booth and will be happy to discuss the details of how VORPAL might fit your modeling needs.

Tech-X will be presenting the following poster:

Poster Session 3: Biological Applications, Accelerators, High Power Microwaves and Radiating Structures, Energy Storage Devices, Analytical Methods, Modeling, and Simulations

Wednesday, May 26, 2010 1:30 – 3:00 PM Exhibit Area

3P60

HIGH-GRADIENT RF BOX CAVITY BREAKDOWN SIMULATIONS USING 3-D PARTICLE TRACKING CODE VORPAL

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